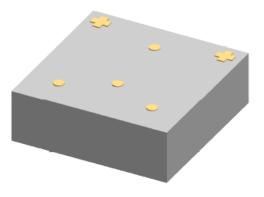


#### Description

The SBD Series of Back (Tunnel) Diodes are fabricated on planar germanium substrates. They are available as die or hermetically packaged.

#### **Features**

- · Excellent temperature stability
- Bias not required
- · Wide video bandwidth



#### Applications

These devices require zero bias as a detector diode and are available in 5 values with varying sensitivity and video impedance.

## Absolute Maximum Ratings<sup>1,2</sup>

Parameter	Absolute Maximum		
P <sub>IN</sub>	+17dBm		
Mounting Temperature	+320°C for 10 seconds		
Operating Temperature	-55°C to +110°C		
Storage Temperature	-65°C to +125°C		
Moisture Sensitivity Rating	MSL 1		

1. Exceeding any one or combination of these limits may cause permanent damage to this device.

2. SemiGen does not recommend sustained operation near these survivability limits.

#### **Static Sensitivity**

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

#### **Moisture Sensitivity**

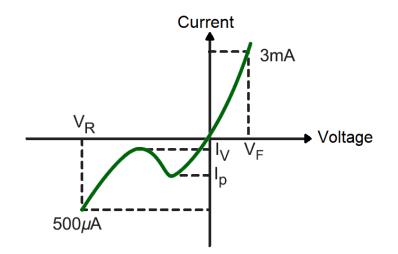
SemiGen die are MSL 1.



## **Electrical Specification**

	I <sub>P</sub>	C <sub>J*</sub>	К	Rv	I <sub>P</sub> /I <sub>V</sub>	V <sub>R</sub>	VF	
Conditions		V <sub>R</sub> =Vv f=100MHz	P <sub>IN</sub> =-20dBm R <sub>L</sub> =10kΩ, f=10GHz			I <sub>R</sub> =500uA	I <sub>F</sub> =3mA	
Part	(uA)	pF (Max)	mV/mW (Typ.)	Ω (Typ.)	(Min)	mV(Min)	mV(Max)	
SBD1057-XX	100-200	0.30	1000	180	2.5	420	135	
SBD2057-XX	200-300	0.30	750	130	2.5	410	130	
SBD3057-XX	300-400	0.30	500	80	2.5	400	125	
SBD4057-XX	400-500	0.30	275	65	2.5	400	120	
SBD5057-XX	500-600	0.30	250	60	2.5	400	110	
For packaged devices add 0.25pF to calculate total capacitance (C <sub>τ</sub> )								

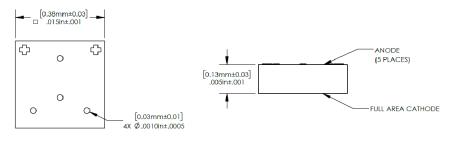
### **IV Curve**



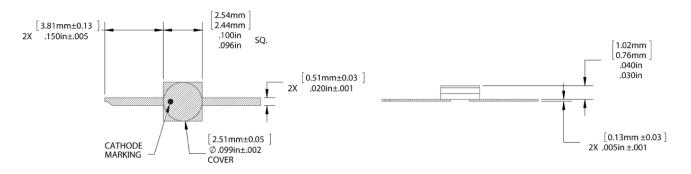


### Outlines

#### **PK18**



#### PK20

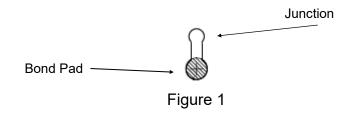


### **Assembly Information**

These germanium diodes are sensitive to the mechanical pressures present during assembly. Use the process parameters below to avoid damaging devices.

Die Attach: Conductive silver epoxy with a maximum cure temperature of +125°C

Wire Bonding: Bond to the offset bond pad as to not damage the junction 0.7 mil thermocompression wedge bond Stage Temp: +155°C; device exposed to these temps for <20 seconds Tip temperature: +160°C maximum



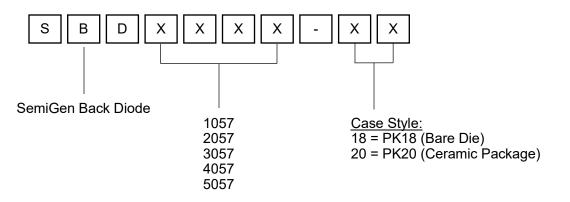
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DS 19974 Rev C



### **Ordering Information**



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